

CLAIMS

1. A pretreatment method for electroless plating, comprising:
- 5 adding an inorganic filler to a polymeric material;
molding the material to obtain a polymeric mold;
irradiating the mold with a laser;
and
immersing the mold in a noble metal aqueous solution.
- 10 2. The pretreatment method for electroless plating according to claim 1, wherein 10-50 weight % of the inorganic filler is added.
- 15 3. The pretreatment method for electroless plating according to claim 1 or 2, wherein a total energy inputted by the laser to the mold is 10-500 J/cm².
- 20 4. The pretreatment method for electroless plating according to claim 1 or 2, wherein the laser is irradiated on an area of the mold so that a fluence and the number of times of irradiation are set to obtain a charging state suitable for precipitating noble metal on the irradiated area.
- 25 5. The pretreatment method for electroless plating according to claim 1 or 2, wherein the polymeric material is selected from the group consisting of a liquid crystal polymer, polyethersulfone, polybutylene terephthalate, polycarbonate, polyphenylene ether, polyphenylene oxide,
30 polyacetal, polyethylene terephthalate, polyamide, ABS, polyphenylene sulfide, polyetherimide, polyetherether

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ketone, polysulfone, polyimide, epoxy resin and composite resins thereof.

5 6. The pretreatment method for electroless plating according to claim 1 or 2, wherein the polymeric material comprises two or more kinds of resins having different laser ablation threshold values.

10 7. The pretreatment method for electroless plating according to claim 1 or 2, wherein a palladium aqueous solution is used as the noble metal aqueous solution.

15 8. The pretreatment method for electroless plating according to claim 1 or 2, wherein a glass filler is used as the inorganic filler.

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